

46-6060 Economy Version

SMT-Buchsenleisten RM 1,27mm, stehend, 2-reihig – BH 3,6/4,5mm, durchsteckbar
SMT Female Headers, 1.27mm Pitch, Vertical, Double Row – 3.6/4.5mm Profile, Pass Through

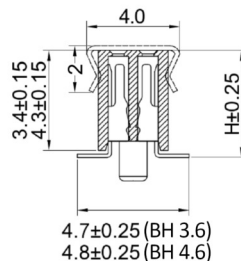
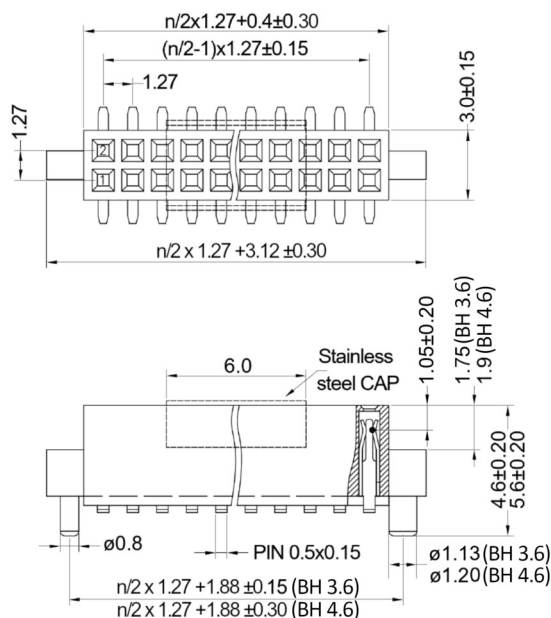
Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Au über Ni
Contact Surface	Au over Ni
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	> 1000 MΩ
Spannungsfestigkeit	500 V AC/DC
Test Voltage	500 V AC/DC
Nennstrom	1 A
Current Rating	1 A
Temperaturbereich	-40 °C ... +105 °C
Temperature Range	-40 °C ... +105 °C
Verarbeitung	230 °C für 30-60 Sekunden (260 °C für 10 Sekunden)
Processing	230 °C for 30-60 seconds (260 °C for 10 seconds)

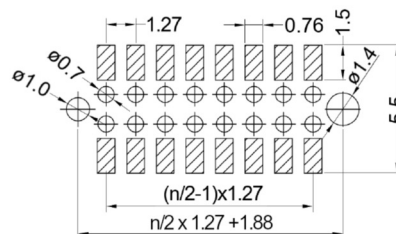


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Doppelfederkontakte für
Vierkantstifte 0,40mm.
Dual beam contacts accept
0.40mm square pins.



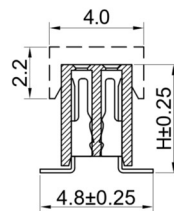
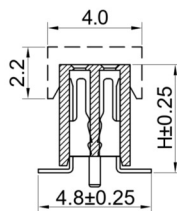
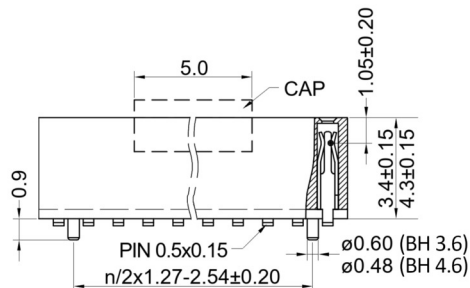
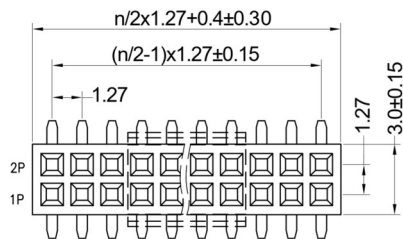
Recommended PCB Layout (Top Side)
(PCB BOARD TOLERANCE ± 0.05)



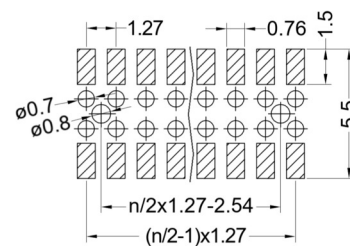
Series	Contacts*	Profile*	Plating	Locating Pegs	Polarisation Key	Packaging*
46-6060	040	36	00	10	00	MPST
	006-080 Zweireihig Double row	36 Bauhöhe 3,60mm Height 3.60mm 46 Bauhöhe 4,60mm Height 4.60mm	00 Vergoldet Gold plated	10 Mit seittl. Pos.hilfen With sideward loc.plegs	00 Nur o. Verpolschutz Only w/o pol.key	ST MPST MPTR

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(PCB BOARD TOLERANCE ±0.05)



Series	Contacts*	Profile*	Plating	Locating Pegs*	Polarisation Key	Packaging*
46-6060	020	46	00	20	00	PPST
	006-080 Zweireihig Double row	36 Bauhöhe 3,60mm Height 3.60mm 46 Bauhöhe 4,60mm Height 4.60mm	00 Vergoldet Gold plated	00 Ohne Pos.hilfen W/o loc. pegs 20 Mit Pos.hilfen With loc. pegs	00 Nur o. Verpolschutz Only w/o pol. key	ST PPST PPTR

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads

MPST In Stangen mit Metal-Pads / In tubes with Metal-Pads

MPTR Tape & Reel mit Metal-Pads / Tape & Reel with Metal-Pads

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads

PPST In Stangen mit Pick&Place-Pads / In tubes with Pick&Place-Pads

PPTR Tape & Reel mit Pick&Place-Pads / Tape & Reel with Pick&Place-Pads

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.

* This is an **order example** -
please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

